

**PRESS STATEMENT/ SIARAN AKHBAR**

(FOR IMMEDIATE RELEASE)

**OXFORD INNOTECH 1QFY26 PAT MORE THAN TRIPLES  
QoQ TO RM3.3 MILLION**

*~ Revenue rises 40.7% QoQ, mainly supported by semiconductor and data centre segment deliveries*

**Kuala Lumpur, 22 May 2026** – Integrated engineering solutions provider, Oxford Innotech Berhad (“OXB” or the “Group”) (牛津科创有限公司), has today announced the financial results for its first quarter ended 31 March 2026 (“1QFY26”).

OXB recorded revenue of RM17.8 million in 1QFY26, representing a 40.7% increase quarter-on-quarter (“QoQ”) from RM12.7 million in the immediate preceding quarter (“4QFY25”), mainly supported by contributions from a customer in the data centre industry for the supply of precision steel and metal components for data centre airflow management system, as well as the semiconductor segment. On a year-on-year (“YoY”) basis, revenue was lower compared to RM19.5 million in 1QFY25.

Segmentally, 1QFY26 revenue was primarily contributed by customers in the semiconductor, electrical and electronics, industrial products and data centre industries, partially offset by lower contributions from customers in the modular building systems and ergonomic furniture industries.

In terms of geographical exposure, Malaysia remained the Group’s largest market, contributing RM12.8 million, or 71.6% of total revenue, while exports contributed the remaining 28.4%, mainly from other Asian countries, North America, and Europe.

Profitability-wise, 1QFY26 PAT more than tripled QoQ to RM3.3 million from RM1.0 million in 4QFY25, with PAT margin improving to 18.2% from 8.0% earlier. Meanwhile, the PAT remained broadly similar YoY when compared to the RM3.2 million achieved in 1QFY25.

**Managing Director of OXB, Mr. Ng Thean Gin (黄天仁)**, commented, “Our first quarter results marked a good start to the new fiscal year for OXB. It reflects the early progress of the Group’s efforts to broaden our exposure to higher-growth segment

such as the data centres, while continuing to leverage our core engineering and precision manufacturing capabilities.”

“Encouragingly, rising demand for advanced computing, AI-related applications and technology infrastructure continues to support activity across the semiconductor and precision engineering value chain. This has strengthened engagement with semiconductor customers, while our data centre projects continue to progress steadily, providing a platform to demonstrate our technical capabilities and establish our track record in supporting mission-critical infrastructure.”

As at 31 March 2026, the Group’s order backlog increased to RM30.0 million from RM21.0 million as at 31 December 2025. To support future growth, OXB plans to commence construction of Penang Science Park Factory 2 Phase 2 in the second half of 2026, which will expand its total manufacturing space by 50.2% to approximately 202,696 sq. ft.

“Looking ahead, our priority is to ensure disciplined execution of orders in hand, deepen customer engagements and continue building capabilities that position OXB for long-term growth. While macroeconomic uncertainties remain, we believe the Group is well-positioned to deliver improved financial performance moving forward, supported by healthy order visibility and favourable long-term industry fundamentals,” Mr. Ng concluded.

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### **About Oxford Innotech Berhad**

Headquartered in Penang, Oxford Innotech Berhad (“**OXB**”) (stock code: OXB/0368), through its subsidiaries, is an integrated engineering solutions provider specialising in precision engineering components solutions, mechanical assembly solutions, and automation and robotic solutions. OXB’s customers comprise primarily multinational and local manufacturers and assemblers across various industries, including semiconductor, electrical and electronics, automotive, and modular building systems.

For more information, please visit <https://oxfordinnotech.com/>

# OXFORD INNOTECH BERHAD

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## **MEDIA CONTACT:**

Brandon Chai Zhe

(M) [brandon@capitalfront.biz](mailto:brandon@capitalfront.biz)